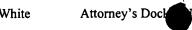
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In the claims:

Please amend the claims as follows:

1. (Currently Amended) A chemical mechanical polishing apparatus, comprising: a substrate holder to hold a substrate;

a polishing belt having a polishing surface to contact at least a portion of the substrate held by the substrate holder while the polishing belt is moving in a first direction in a generally linear path relative to the substrate, the polishing belt having a plurality of grooves formed therein, the grooves having a depth of at least about 0.02 inches, a width of at least about 0.015 inches, and a pitch of at least about 0.09 inches oriented substantially perpendicular to the first direction of motion; and

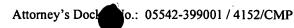
a backing member positioned on a side of the polishing belt opposite the substrate holder.

- 2. (Original) The apparatus of claim 1 wherein the grooves are uniformly spaced over the polishing surface.
- 3. (Original) The apparatus of claim 1 wherein the grooves have a depth between about 0.02 and 0.05 inches.
- 4. (Original) The apparatus of claim 3 wherein the grooves have a depth of approximately 0.03 inches.
- 5. (Original) The apparatus of claim I wherein the grooves have a width between about 0.015 and 0.04 inches.
- 6. (Original) The apparatus of claim 5 wherein the grooves have a width of approximately 0.02 inches.
- 7. (Original) The apparatus of claim 1 wherein the grooves have a pitch between about 0.09 and 0.24 inches.



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8. (Original) The apparatus of claim 7 wherein the grooves have a pitch of approximately 0.12 inches.

- 9. (Original) The apparatus of claim l, further comprising an actuator to urge the substrate and the belt into contact with one another for polishing.
- 10. (Currently Amended) The apparatus of claim l wherein a fluid layer is interposed between the membrane backing member and the polishing belt.
- 11. (Original) The apparatus of claim 1 wherein the belt has a width at least as wide as the substrate holder.
- 12. (Original) The apparatus of claim 1 wherein the belt is driven continuously during polishing.
- 13. (Original) The apparatus of claim 1 wherein the belt is driven periodically between polishing operations.
 - 14. (Original) The apparatus of claim 1 wherein the belt is a continuous belt.
- 15. (Original) The apparatus of claim 1 wherein the belt extends between a feed and a take-up roller.
 - 16. Cancelled.
- 17. (Currently Amended) The apparatus of claim 1 wherein the grooves include a first plurality of substantially linear grooves and a second plurality of substantially linear grooves oriented perpendicular to the first plurality of grooves further comprising a second plurality of grooves oriented substantially perpendicular to the plurality of grooves.



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18. (Original) The apparatus of claim 1 wherein the grooves have an arcuate shape curved away from the first direction of motion.

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- 19. Cancelled.
- 20. (Currently Amended) The apparatus of claim 191, wherein the plurality of grooves are substantially linear.
 - 21. (Original) A chemical mechanical polishing apparatus, comprising: a substrate holder to hold a substrate;

a polishing belt having a polishing surface to contact at least a portion of the substrate held by the substrate holder, the polishing belt movable in a first direction in a generally linear path relative to the substrate, the polishing belt having a first plurality of substantially linear grooves and a second plurality of substantially linear grooves formed therein, the first plurality of grooves oriented substantially perpendicular to the second plurality of grooves; and

a backing member positioned on a side of the polishing belt opposite the substrate holder.

- 22. (Original) The apparatus of claim 21 wherein the first plurality of grooves is oriented substantially perpendicular to the first direction.
- 23. (Original) The apparatus of claim 21 wherein the first and second pluralities of grooves are oriented at about 45 degrees to the first direction.
 - 24. (Original) A chemical mechanical polishing apparatus, comprising: a substrate holder to hold a substrate;

a polishing belt having a polishing surface to contact at least a portion of the substrate held by the substrate holder, the polishing belt movable in a first direction in a generally linear path relative to the substrate, the polishing belt having a plurality of arcuate grooves formed therein, the grooves oriented substantially perpendicular to the first direction of motion; and



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a backing member positioned on a side of the polishing belt opposite the substrate holder.

25. (Original) The apparatus of claim 24 wherein the arcuate grooves are bowed away from the first direction.